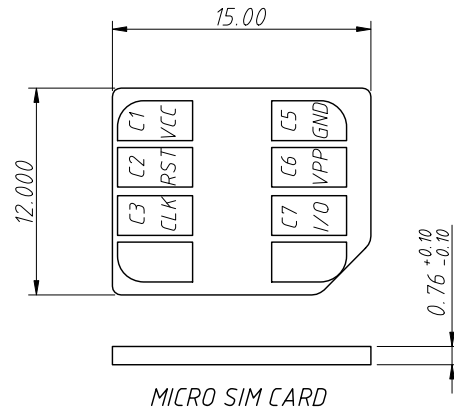
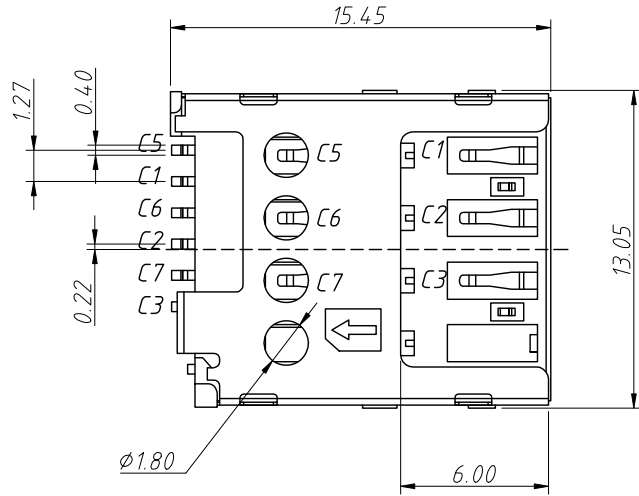
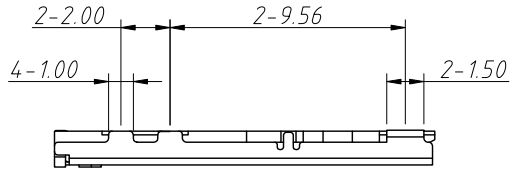


REV	SYM	Revision Record	Appr.	Date
V0	KLS01338	New Version Release	Song	2025-08-09



MICRO SIM CARD

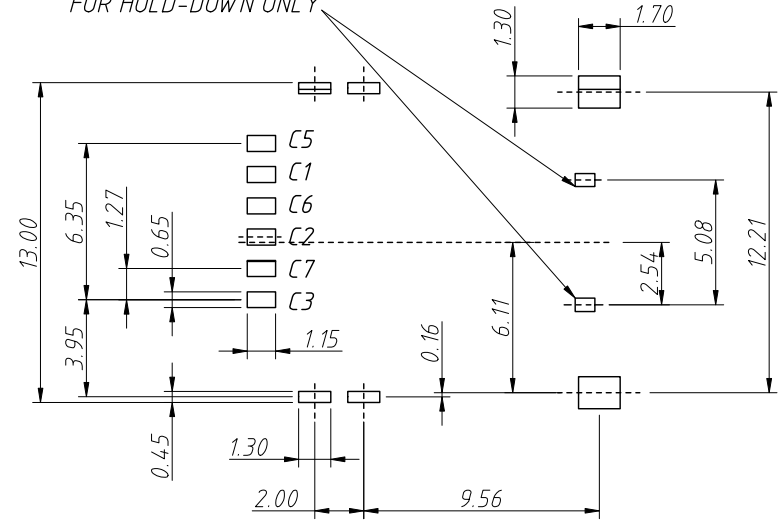
Material:

Insulator: LCP High Temperature Thermoplastic, UL 94V-0.
Contact:C5210,Plated 50u" Ni Overall,Contact Au 1u,Pad Au 1u"
Shell:SUS,Plated 50u" Ni Overall,Pad Au 1u"

Electrical:

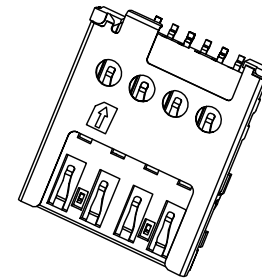
Current Rating :0.5Amps Max
Voltage Rating :125V AC/DC
Ambient Temperature :-40°C ~+85°C
Storage Temperature :-40°C ~+85°C
Ambient Humidity :95% R.H. Max
Contact Resistance:100mΩ Max
Insulation Resistance:1000MΩMin./500VDC
Mating Cycles:10000 Insertions
Reflow peak temp.: 260°C ±5°C,35 S

NOT GND
FOR HOLD-DOWN ONLY



PCB Solder area

Recommended PCB Layout
Tolerance:±0.05mm



SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

ANGLE TOLERANCE		PROJECTION		Description:	
±3°				Micro SIM Card Connector	
GENERAL TOLERANCE		UNITS	mm	KLS P/N:	L-KLS1-SIM-046-6P-R
x.x	±0.30	SHEET SIZE	A4		
x.xx	±0.20	Draw:	Song	2025-08-09	
x.xxx	±0.10	Check:	Daniel	2025-08-09	



NingBo KLS ELECTRONIC CO.,LTD.